

1PS76SB10

Schottky barrier single diode

17 December 2012

Product data sheet

1. General description

Planar Schottky barrier diode with an integrated guard ring for stress protection, encapsulated in a very small SOD323 Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Low capacitance
- AEC-Q101 qualified

3. Applications

- Ultra high-speed switching
- Line termination
- Voltage clamping
- Reverse polarity protection

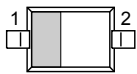


4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current		-	-	200	mA
V_R	reverse voltage		-	-	30	V
V_F	forward voltage	$I_F = 10 \text{ mA}$; pulsed; $t_p = 300 \mu\text{s}$; $\delta = 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	400	mV

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SOD323	 K  A aaa-003679
2	A	anode		

[1] The marking bar indicates the cathode.



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6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
1PS76SB10	SOD323	plastic surface-mounted package; 2 leads	SOD323

7. Marking

Table 4. Marking codes

Type number	Marking code
1PS76SB10	S0

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	30	V
I_F	forward current		-	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	300	mA
I_{FSM}	non-repetitive peak forward current	$t_p < 10$ ms; $T_{j(\text{init})} = 25$ °C	-	600	mA
T_j	junction temperature		-	125	°C
T_{amb}	ambient temperature		-55	125	°C
T_{stg}	storage temperature		-65	150	°C

9. Thermal characteristics

Table 6. Thermal characteristics

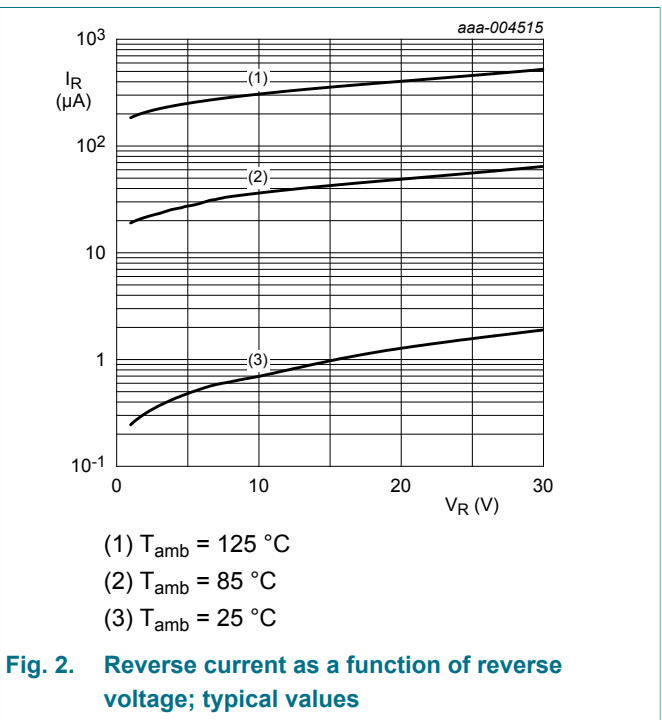
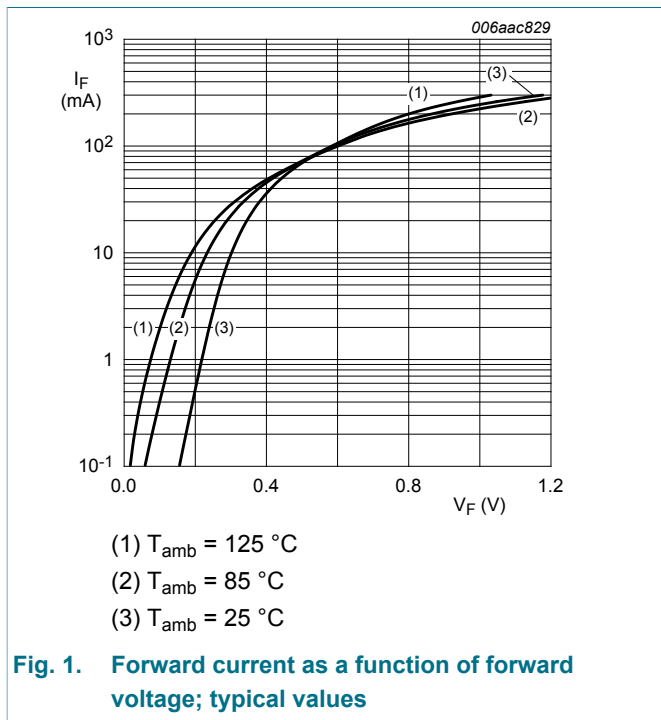
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{\text{th}(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	450	K/W

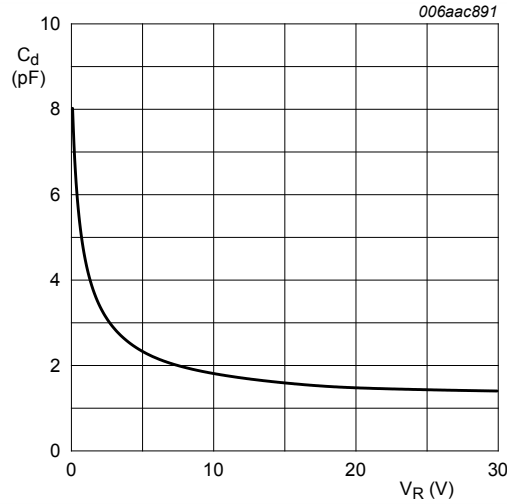
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage	I _F = 0.1 mA; pulsed; t _p = 300 μs; δ = 0.02; T _{amb} = 25 °C	-	-	240	mV
		I _F = 1 mA; pulsed; t _p = 300 μs; δ = 0.02; T _{amb} = 25 °C	-	-	320	mV
		I _F = 10 mA; pulsed; t _p = 300 μs; δ = 0.02; T _{amb} = 25 °C	-	-	400	mV
		I _F = 30 mA; pulsed; t _p = 300 μs; δ = 0.02; T _{amb} = 25 °C	-	-	500	mV
		I _F = 100 mA; pulsed; t _p = 300 μs; δ = 0.02; T _{amb} = 25 °C	-	-	800	mV
I _R	reverse current	V _R = 25 V; pulsed; t _p = 300 μs; δ = 0.02; T _{amb} = 25 °C	-	-	2	μA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _{amb} = 25 °C	-	-	10	pF





T_{amb} = 25 °C; f = 1 MHz

Fig. 3. Diode capacitance as a function of reverse voltage; typical values

11. Test information

11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

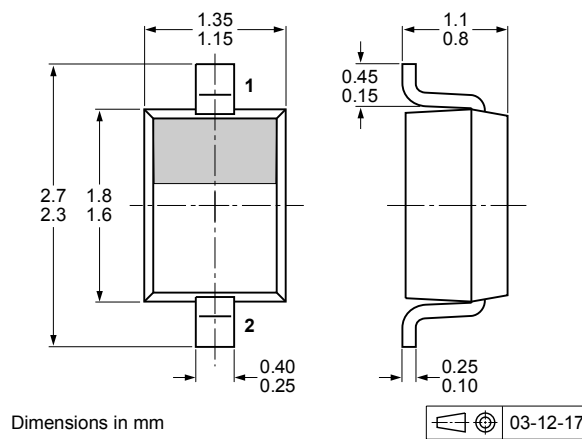


Fig. 4. Package outline SOD323

13. Soldering

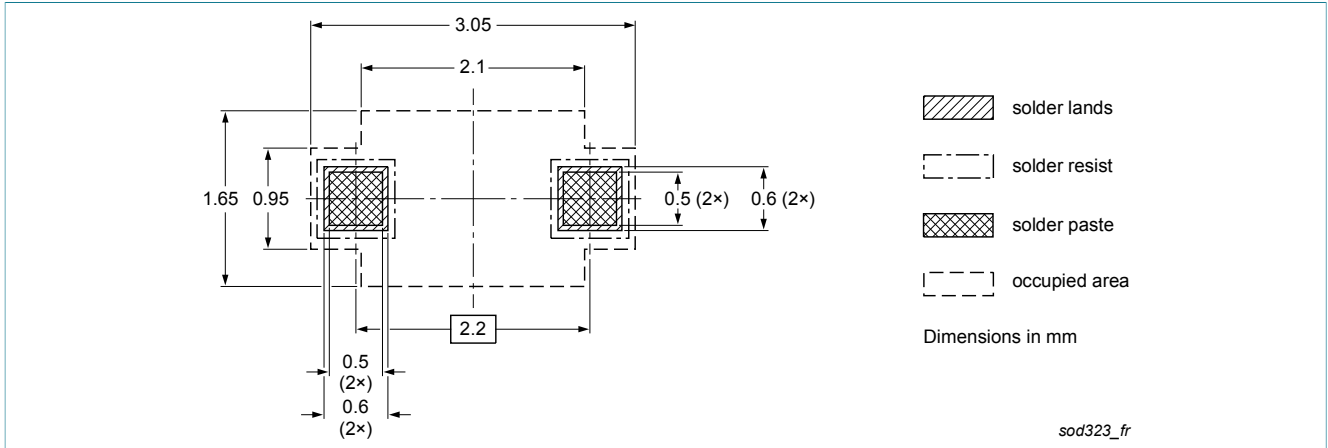


Fig. 5. Reflow soldering footprint for SOD323

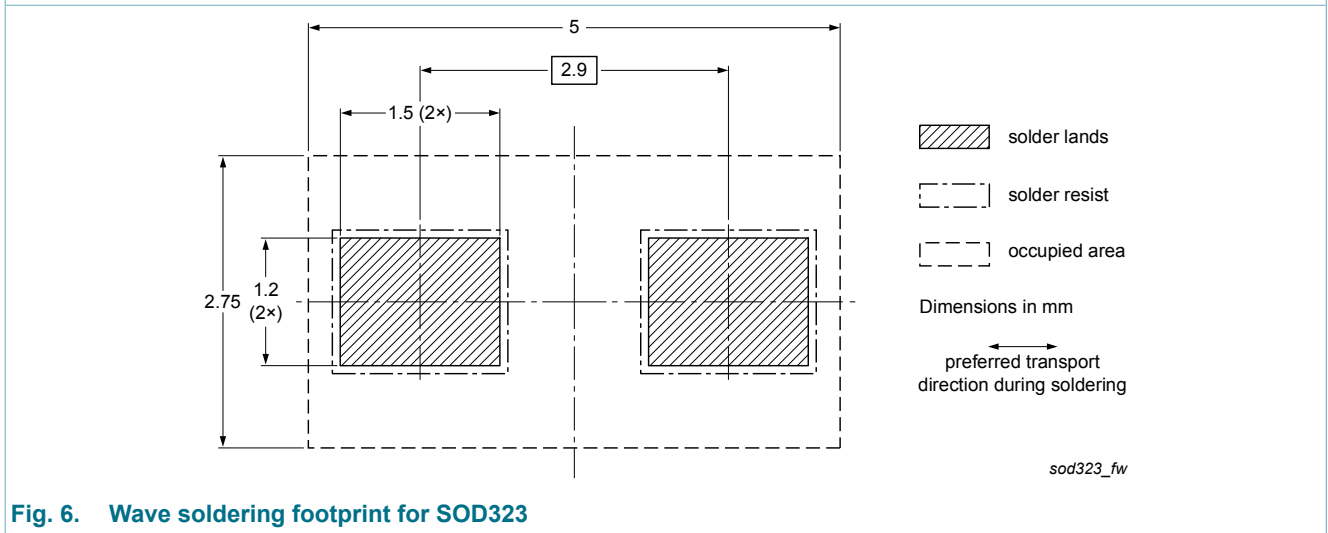


Fig. 6. Wave soldering footprint for SOD323

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
1PS76SB10 v.4	20121217	Product data sheet	-	1PS76SB10 v.3
Modifications:	<ul style="list-style-type: none"> Section "Features and benefits" updated Section "Applications" updated Table 5 "Limiting values": ambient temperature T_{amb} minimum value updated Table 7 "Characteristics": forward voltage V_F conditions updated Figures 1, 2 and 3 updated 			
1PS76SB10 v.3	20120718	Product data sheet	-	1PS76SB10 v.2
1PS76SB10 v.2	20040126	Product specification	-	1PS76SB10 v.1
1PS76SB10 v.1	19961014	Product specification	-	-

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15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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